

IN THE SPECIFICATION:

Please amend the specification as follows:

Please amend the third paragraph on page 4, as follows:

Fig. 1(a) is a sectional view at line I-I' A-A' showing a schematic structure of a module component in embodiment 1 of the invention, and Fig. 1(b) is a top view of the component. In the diagrams, reference numeral 1 denotes a resin substrate. In the substrate, chip resistors 2, chip capacitors 3, and other chip components are inserted into penetration holes having the nearly same hole shapes as chip components, and their end electrodes and circuit wirings 4a and 4b formed on both sides of resin substrate 1 are electrically coupled to compose a desired electric circuit. They are held and reinforced between first auxiliary substrate 5 and second auxiliary substrate 6. IC chip 7 and electronic components 8 that are hardly reduced in size are mounted on first auxiliary substrate 5 and are electrically coupled to wiring circuit 4c and further to circuit wiring 4a through conductor filling in through-holes 9. Reference numeral 7a denotes a molding resin, 10 denotes an external electrode terminal on module component 11.